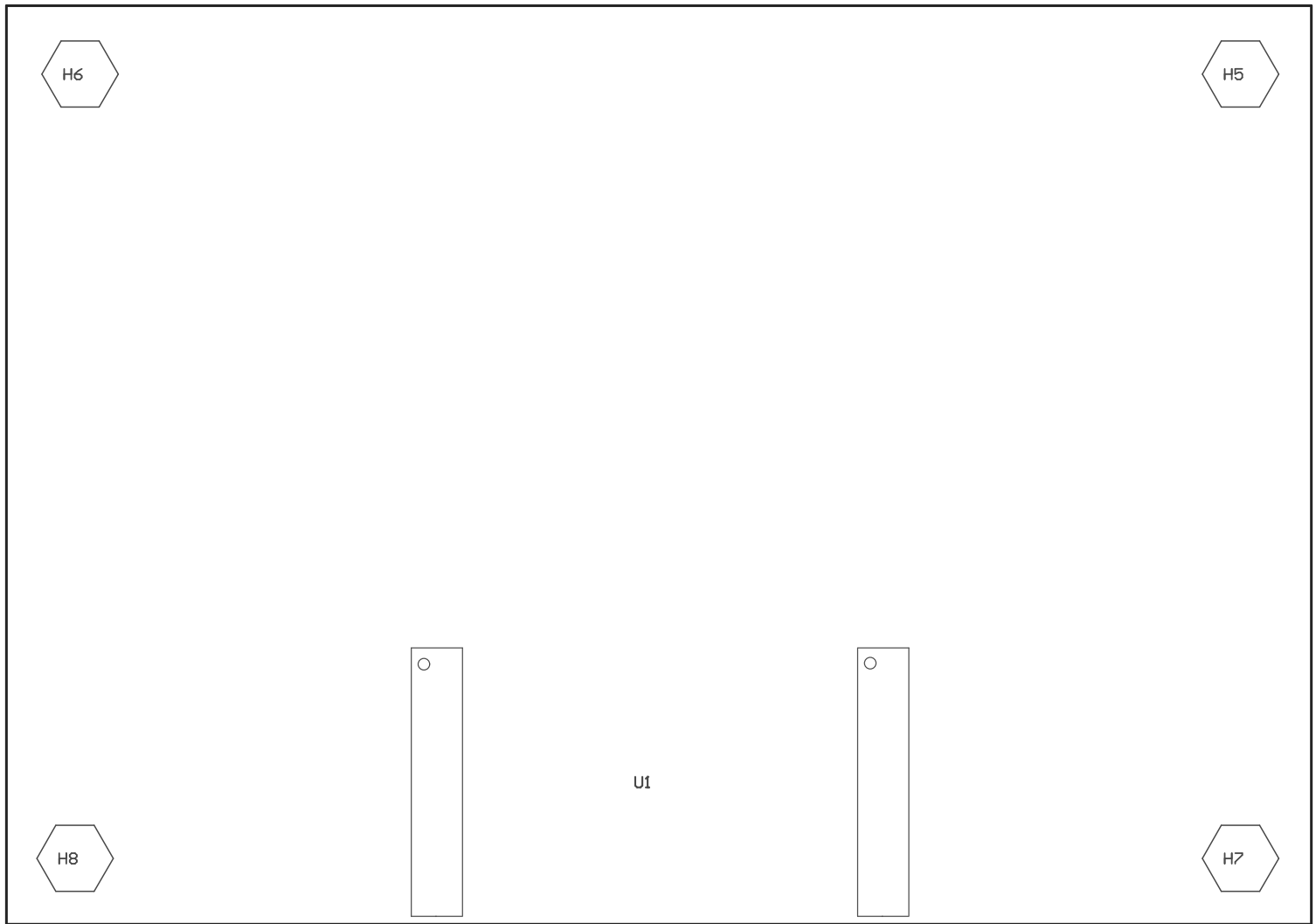


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

| | | | |
|----------------------------------|-----------------------|------------|---------------------------------|
| PCB VIEWED FROM TOP SIDE | BOARD #: SAT0103 | REV: E1 | SUN REV: Not In Version Control |
| IGNORE -> Top Overlay | | | |
| PLOT NAME = Top Assembly Drawing | GENERATED : 7/14/2014 | 4:17:18 PM | TEXAS INSTRUMENTS |



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

| | | | |
|-------------------------------------|----------------------------------|---------|--------------------------------|
| PCB VIEWED FROM BOTTOM SIDE | BOARD #: SAT0103 | REV: E1 | SUN REV: Not In VersionControl |
| IGNORE -> | | | |
| PLOT NAME = Bottom Assembly Drawing | GENERATED : 7/14/2014 4:17:19 PM | | TEXAS INSTRUMENTS |

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